

## C1812C473F2TACTU

Aliases (C1812C473F2TAC7800)

SMD Comm X8G HT150C, Ceramic, 0.047 uF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information			
Series	SMD Comm X8G HT150C		
Style	SMD Chip		
Description	SMD, MLCC, High Temperature, Ultra-Stable		
Features	High Temperature, Ultra-Stable		
RoHS	Yes		
Termination	Tin		
Marking	No		
AEC-Q200	No		
Typical Component Weight	67 mg		
Shelf Life	78 Weeks		
MSL	1		

Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
Т	1.25mm +/-0.15mm
S	2.3mm MIN
В	0.6mm +/-0.35mm

I	1.25mm +/-0.15mm		
S	2.3mm MIN		
В	0.6mm +/-0.35mm		
Packaging Specifications			
Packaging	T&R, 180mm, Plastic Tape		

1000

Packaging Quantity

Specifications			
Capacitance	0.047 uF		
Measurement Condition	1 kHz 1.0Vrms		
Tolerance	1%		
Voltage DC	200 VDC		
Dielectric Withstanding Voltage	500 VDC		
Temperature Range	-55/+150°C		
Temp. Coefficient	X8G		
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms		
Dissipation Factor	0.1% 1 kHz 1.0Vrms		
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours		
Insulation Resistance	21.2766 GOhms		

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